

Title (en)
DEFECTIVITY AND PROCESS CONTROL OF ELECTROLESS DEPOSITION IN MICROELECTRONICS APPLICATIONS

Title (de)
DEFEKTIVITÄTS- UND PROZESSSTEUERUNG DER STROMLOSEN ABLAGERUNG IN MIKROELEKTRONIK-ANWENDUNGEN

Title (fr)
DÉFLEXION ET COMMANDE DE PROCESSUS DE DÉPOSITION AUTOCATALYTIQUE DANS DES APPLICATIONS MICROÉLECTRONIQUES

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Application
EP 06814944 A 20060919

Priority

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- US 24387605 A 20051005

Abstract (en)
[origin: WO2007035731A2] Methods and compositions for electrolessly depositing Co, Ni, or alloys thereof onto a substrate in manufacture of microelectronic devices. Grain refiners, levelers, oxygen scavengers, and stabilizers for electroless Co and Ni deposition solutions.

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H01L 21/3205 (2006.01)

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Citation (search report)
See references of WO 2007035731A2

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